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31 March 2006

Daniel Gamota
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Re: P1620.2 - Standard Methods for the Characterization of Printed and Organic Diode Bridge Structures for RF Devices

Dear Daniel:

I am pleased to inform you that on 30 March 2006 the IEEE-SA Standards Board approved the above referenced project until 31 December 2010. A copy of the file can be found on our website at <http://standards.ieee.org/board/nes/projects/1620-2.pdf>.

Now that your project has been approved, please forward a roster of participants involved in the development of this project. This request is in accordance with the IEEE-SA Operations Manual, Clause 5.1.2i under Duties of the Sponsor which states:

"Submit annually to the IEEE Standards Department an electronic roster of individuals participating on standards projects"

For your convenience, an Excel spreadsheet for your use has been posted on our website at <http://standards.ieee.org/guides/par/roster.xls>. Please forward this list to me via e-mail at j.haasz@ieee.org no later than 28 June 2006.

Please visit our website, IEEE Standards Development Online (<http://standards.ieee.org/resources/development/index.html>), for tools, forms and training to assist you in the standards development process. Also, we strongly recommend that a copy of your draft be sent to this office for review prior to the final vote by the working group to allow for a quick review by editorial staff before sponsor balloting begins.

If you should have any further questions, please contact me at 732-562-6367 or by email at j.haasz@ieee.org.

Sincerely,

Jodi Haasz
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International Stds Programs and Governance
Standards Activities
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CC: paul.brazis@motorola.com

PAR FORM

PAR Status: New PAR

PAR Approval Date: 30 March 2006

PAR Signature Page on File: Yes

1. Assigned Project Number: P1620.2

2. Sponsor Date of Request: 2006-02-21

3. Type of Document: Standard for

4. Title of Document:

Draft: Standard Methods for the Characterization of Printed and Organic Diode Bridge Structures for RF Devices

5. Life Cycle: Full-Use

6. Type of Project:

6a. Is this an update to an existing PAR? No

6b. The Project is a: New Standard

7. Working Group Information:

Name of Working Group: Printed and Organic RF Electronics Working Group

Approximate Number of Expected Working Group Members:20

8. Contact information for Working Group Chair:

Name of Working Group Chair: Paul Brazis

Telephone: 847-756-1561 **FAX:**

Email: paul.brazis@motorola.com

9. Contact information for Co-Chair/Official Reporter, Project Editor or Document Custodian if different from the Working Group Chair:

Name of Co-Chair/Official Reporter, Project Editor or Document Custodian:

Telephone: **FAX:**

Email:

10. Contact information for Sponsoring Society or Standards Coordinating Committee:

Name of Sponsoring Society and Committee: IEEE Nanotechnology Council Standards Committee

Name of Sponsoring Committee Chair: Daniel Gamota

Telephone: 847-576-5084 **FAX:** 847-576-2111

Email: gamota@motorola.com

Name of Liaison Rep. (if different from the Sponsor Chair):

Telephone: **FAX:**

Email:

Name of Co-Sponsoring Society and Committee: IEEE Computer Society Microprocessors and Microcomputers

Name of Co-Sponsoring Committee Chair: Bob Davis

Telephone: 408-353-2706 **FAX:** 408-353-8116

Email: bob@scsi.com

Name of Liaison Rep. (if different from the Sponsor Chair):

Telephone: **FAX:**

Email:

11. The Type of ballot is: Individual Sponsor Ballot

Expected Date of Submission for Initial Sponsor Ballot: August 2007

12. Projected Completion Date for Submittal to RevCom: February 2008

Target Extension Request Information for a Modified PAR whose completion date is being extended past the original four-year life of the PAR:

13. Scope of Proposed Project:

This standard describes standard methods for the characterization of printed and organic diode bridges for RF devices. The methods are independent of processing routes used to fabricate the electronic devices.

Is the completion of this document contingent upon the completion of another document? No

14. Purpose of Proposed Project:

The purpose of this standard is to provide and suggest procedures for characterization and reporting of data. These methods are described for use as a uniform reporting standard that is intended to be applicable for characterizing and reporting both research results and manufacturing data, with its primary use expected to shift as printed electronics technology matures. The standard recommends the necessary tools and procedures for validation.

15. Reason for the Proposed Project:

There is currently no defined standard for the characterization of printed and organic diode bridge structures for RF devices and the means of reporting performance and other data. Without openly defined standard test methods the acceptance and diffusion of printed and organic electronics RF technology will be severely impeded. This standard would be used by designers and producers of printed- and organic-based RF products, including electrical designers and OEMs. This standard also will be used by scientists and engineers performing studies at academic institutions and at government laboratories.

16. Intellectual Property:

- a. **Has the IEEE-SA policy on intellectual property been presented to those responsible for preparing/submitting this PAR?** Yes 2006-01-31
- b. **Is the sponsor aware of copyright permissions needed for this project?** No
- c. **Is the sponsor aware of trademarks that apply to this project?** No
- d. **Is the sponsor aware of possible registration activity related to this project?** No

17. Are there other documents or projects with a similar scope? No**Similar Scope Project Information:****18. Is there potential for this document (in part or in whole) to be adopted by another national , regional or international organization?** Do not know at this time

If yes, the following questions must be answered:

Organization Name?

Technical

Committee

International

Contact

Information?

19. Will this project result in any health, safety, or environmental guidance that affects or applies to human health or safety? No

If yes, please explain:

20. Sponsor Information

- a. **Is the scope of this project within the approved/scope/definition of the Sponsor's Charter?** Yes

If no, please explain:

- b. **The Sponsor's procedures have been accepted by the IEEE-SA Standards Board Audit Committee?** Yes

21. Additional Explanatory Notes: (Item Number and Explanation)

